



Product/Process Change Notice - PCN 08_0068 Rev. A

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Material Report). Any issues with this PCN or requirements to qualify the change (additional data or samples) must be sent to ADI within 30 days of receiving this notification. The information contained within this PCN is considered proprietary and should not be shared outside of your company. ADI contact information is listed below.

Note: Revised fields are indicated by a red field name. See Appendix B for revision history.

PCN Title: ADM705/ADM706/ADM708 Wafer Fab Process Transfer for SOIC Models

Publication Date: 30-Jun-2009

Samples Available Date:

Effectivity Date: 29-Jun-2009 *(the earliest date that a customer could expect to receive changed material)*

Description Of Change

From: Manufactured on 1.2U-SC-13L-D8 wafer fab process in TSMC, Taiwan.
To: Manufactured on 0.50C2P3M50.00 wafer fab process in TSMC, Taiwan.

1. Shipment of new parts will not take place until after November 1st 2008.
2. For date codes after 0846 parts will be new die and parts prior to and including date codes 0846 are the old die.

Reason For Change

Improve manufacturability

Impact of the change (positive or negative) on fit, form, function & reliability

The changes to the device will not impact form, fit, function, quality or reliability.

Product Identification *(this section will describe how to identify the changed material)*

The date code of the first changed lots is 0847.

Summary of Supporting Information

Qualification report RQR04310A is attached. Samples are available on request.

Supporting Documents

Attachment 1: ADI_PCN_08_0068_Rev_A_RQR04310A.pdf

For questions on this PCN, send email to the regional contacts below or contact your local ADI sales representative

Americas: PCN_Americas@analog.com

Europe: PCN_Europe@analog.com

Japan: PCN_Japan@analog.com

Rest of Asia: PCN_ROA@analog.com

Appendix A - Affected ADI Models

Existing Parts - Product Family / Model Number (50)

ADM705 / AD51/090-0	ADM705 / AD51/090Z-0REEL	ADM705 / ADM705AR	ADM705 / ADM705AR-REEL	ADM705 / ADM705AR-REEL7	ADM705 / ADM705ARZ
ADM705 / ADM705ARZ-REEL	ADM705 / ADM705ARZ-REEL7	ADM706 / AD51/080-0REEL7	ADM706 / AD51/080Z-0REEL7	ADM706 / ADM706AR	ADM706 / ADM706AR-REEL
ADM706 / ADM706AR-REEL7	ADM706 / ADM706ARZ	ADM706 / ADM706ARZ-REEL	ADM706 / ADM706ARZ-REEL7	ADM706 / ADM706PAR	ADM706 / ADM706PAR-REEL
ADM706 / ADM706PARZ	ADM706 / ADM706PARZ-REEL	ADM706 / ADM706RAR	ADM706 / ADM706RAR-REEL	ADM706 / ADM706RAR-REEL7	ADM706 / ADM706RARZ
ADM706 / ADM706RARZ-REEL	ADM706 / ADM706RARZ-REEL7	ADM706 / ADM706SAR	ADM706 / ADM706SAR-REEL	ADM706 / ADM706SARZ	ADM706 / ADM706SARZ-REEL
ADM706 / ADM706TAR	ADM706 / ADM706TAR-REEL	ADM706 / ADM706TARZ	ADM706 / ADM706TARZ-REEL	ADM708 / ADM708AR	ADM708 / ADM708AR-REEL
ADM708 / ADM708ARZ	ADM708 / ADM708ARZ-REEL	ADM708 / ADM708RAR	ADM708 / ADM708RAR-REEL	ADM708 / ADM708RARZ	ADM708 / ADM708RARZ-REEL
ADM708 / ADM708SAR	ADM708 / ADM708SAR-REEL	ADM708 / ADM708SARZ	ADM708 / ADM708SARZ-REEL	ADM708 / ADM708TAR	ADM708 / ADM708TAR-REEL
ADM708 / ADM708TARZ	ADM708 / ADM708TARZ-REEL				

Appendix B - Revision History

Rev	Publish Date	Rev Description
Rev. -	29-Jun-2009	Initial Release
Rev. A	30-Jun-2009	Clarification of the new die package marking, removing the reference to the dot on the package and replacing with a clear date code cut off for identification of the new die material.

Analog Devices, Inc.

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